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Part Number: [0702461001](#)
Status: **Active**
Overview: C-Grid® Products
Description: 2.54mm Pitch C-Grid® Header, Low Profile, Dual Row, Vertical, Shrouded, 10 Circuits, 0.38µm Gold (Au) Selective Plating, Tin (Sn) PC Tail Plating

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

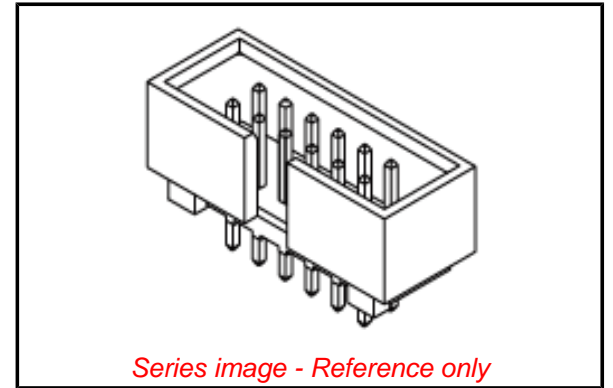
Product Family PCB Headers
 Series 70246
 Application Signal, Wire-to-Board
 Overview C-Grid® Products
 Product Name C-Grid®
 UPC 822348487325

Physical

Breakaway No
 Circuits (Loaded) 10
 Circuits (maximum) 10
 First Mate / Last Break No
 Flammability 94V-0
 Glow-Wire Compliant No
 Guide to Mating Part No
 Keying to Mating Part None
 Lock to Mating Part None
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Net Weight 1.467/g
 Number of Rows 2
 Orientation Vertical
 PC Tail Length 3.43mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 1.60mm
 Packaging Type Tray
 Pitch - Mating Interface 2.54mm
 Pitch - Termination Interface 2.54mm
 Plating min - Mating 0.381µm
 Plating min - Termination 1.905µm
 Polarized to Mating Part Center Slot
 Polarized to PCB No
 Shrouded Fully
 Stackable No
 Surface Mount Compatible (SMC) No
 Temperature Range - Operating -55°C to +120°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 2.5A
 Voltage - Maximum 250V DC



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Yes -ED/39/2015 (15 June 2015)

Acetamide, N-methyl-dinoseb (ISO)

furan

C,C'-

azodi(formamide)

tricosafuorododecanoic acid

heptacosafuorotetradecanoic acid

methoxyacetic acid

1,2-diethoxyethane

henicosafuoroundecanoic acid

sodium

peroxometaborate

pentacosafuorotridecanoic acid

3-ethyl-2-methyl-2-(3-methylbutyl)-1,3-

oxazolidi

Disodium tetraborate

Boric acid

Trixylyl phosphate

4-(1,1,3,3-tetramethylbutyl)phenol,

ethoxylated

Methylhexahydrophthalic anhydride

Sodium perborate;

perboric acid, sodium salt

Silicic acid (H₂Si₂O₅), barium salt (1:1),

lead-

Trichloroethylene

1,2,3-

Trichloropropane

China RoHS

Solder Process Data

Duration at Max. Process Temperature (seconds) 010
Lead-free Process Capability WAVE
Max. Cycles at Max. Process Temperature 001
Process Temperature max. C 235

Material Info**Reference - Drawing Numbers**

Sales Drawing SDA-70246-**20-25_39

1,2-dichloroethane
1-bromopropane
Tris(2-chloroethyl)
phosphate
Boric acid, disodium
salt, hydrate
formamide
4,4'-
bis(dimethylamino)benzophenone
N,N,N',N'-
tetramethyl-4,4'-
methyldianiline
1,2-bis(2-
methoxyethoxy)ethane
[4-[4,4'-
Bis(dimethylamino)benzhydrylidene]cyclo
4,4'-
bis(dimethylamino)-4''-
(methylamino)trityl
Diboron-trioxide
[4-[[4-Anilino-1-
naphthyl]]4-
(dimethylamino)phen
#,#-Bis[4-
(dimethylamino)phenyl]-4
(phenylamino)
diethyl sulphate
propylene oxide

Halogen-Free**Status****Not Low-Halogen****Need more information on product
environmental compliance?**

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any
non-product compliance questions.

China ROHS
ELV

Green Image
Not Relevant

Search Parts in this Series

[70246](#) Series

Mates With

[70450](#) SL™ Crimp Housing, [70058](#) SL™
Crimp Terminal

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